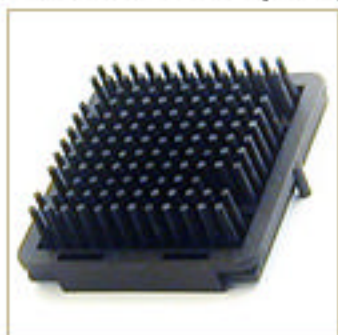




BGA Snap-on Heatsinks

EMULATION TECHNOLOGY, INC.

World Leader in Adapters, Clips, and Test Accessories



Standard BGA product provided as:

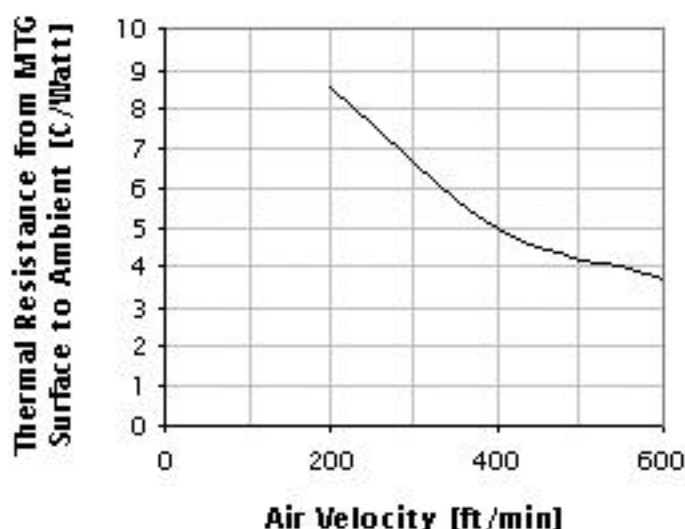
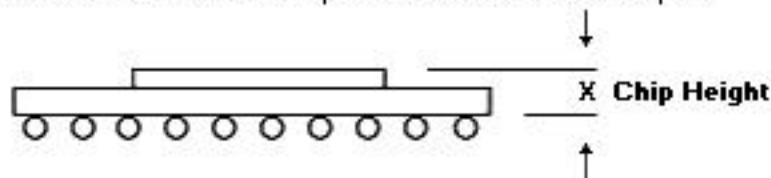
- Black anodized
- Pre-assembled as shown
- Customs available upon request

Other BGA products available:

- Rework Stencils
- Reballing Preforms
- Sockets
- Ultra-mini Pogo Pins

ET Part Number	Part Marking	Chip Pkg. Size (sq)	Heatsink Height	Fits Chip Height [x]
H-3503-07-9038-05-A	HS2132DCAB	35 mm	0.3 in (7.62 mm)	1.88 (+/- 0.26) mm
H-3503-08-9038-05-A	HS2089DCAB	35 mm	0.3 in (7.62 mm)	1.38 (+/- 0.26) mm

* Max dimensions include allowance for .005" thick thermal pad



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— HS2132DCAB HS2089DCAB